

Serial Number : 09/254,769
Filing Date : March 11, 1999
Examiner : V. Nguyen
Group Art Unit : 2829
For :
WAFER SCALE HIGH DENSITY
PROBE ASSEMBLY , APPARATUS FOR
USE THEREOF
AND METHODS OF FABRICATION
THEREOF

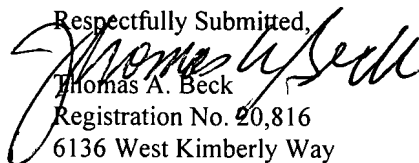
Honorable Commissioner of Patents
and Trademarks
Post Office Box 1450
Alexandria, VA 22313-1450

Sir:

ATTORNEY'S CHANGE OF ADDRESS

Please send all future communications in this application to the undersigned at 6136 West Kimberly Way, Glendale,
AZ 85308-7627.

Respectfully Submitted,



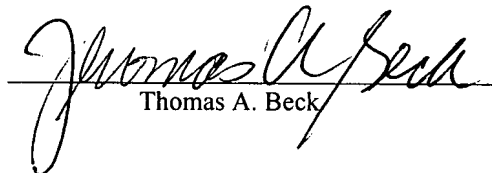
Thomas A. Beck

Registration No. 20,816
6136 West Kimberly Way
Glendale, AZ 85308-7627
Telephone (623) 466 - 0080

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being transmitted by the United States Postal Service, First Class mail
postage prepaid on the date shown below to the United States Patent Office, Post Office Box 1450, Alexandria, VA
22313-1450.

July 7, 2007


Thomas A. Beck